23. The method of claim 22 wherein the algorithm additionally includes a normal distribution function.

24. The method of claim 23 wherein the distance between the microcavities is varied about 1 to 40%.

25. An anisotropic conductive film (ACF) comprising a plurality of conductive particles disposed in predefined non-random particle locations as a non-random array in a monolayer in or on an adhesive layer, wherein said non-random particle locations vary in a controlled with a pre-defined variation manner that is determined using ~~an algorithm employing~~ a random number generator function in order to reduce periodic/ repetitive line defects.

26. The ACF of claim 25 wherein said conductive particles are partially buried in the adhesive layer.

27. The ACF of claim 25 wherein the random number generator function is part of an algorithm that additionally includes a normal distribution function.

28. The ACF of claim 27 wherein the distance between the pre-defined variation ~~microcavities~~ is selected from ~~varied~~ about 1 to 40%.

29. An anisotropic conductive film (ACF) comprising a plurality of conductive particles disposed in predefined non-random particle locations as a non-random array in or on an adhesive layer, wherein the ACF includes an oblique area that is essentially free from conductive particles that corresponds to an oblique line that runs across the ACF; wherein the ACF has an X-Y plane corresponding to its length and width and a Z-axis corresponding to its thickness and the ACF is insulating in the X-Y plane relative to the Z-axis which is conductive.

30. The ACF of claim 29 wherein said conductive particles are partially buried in the adhesive layer.

31. The ACF of claim 29 wherein the ACF is made by the method of claim 3.